

WP11 Reporting period 2

CERN 20 jun 2024

WP 11

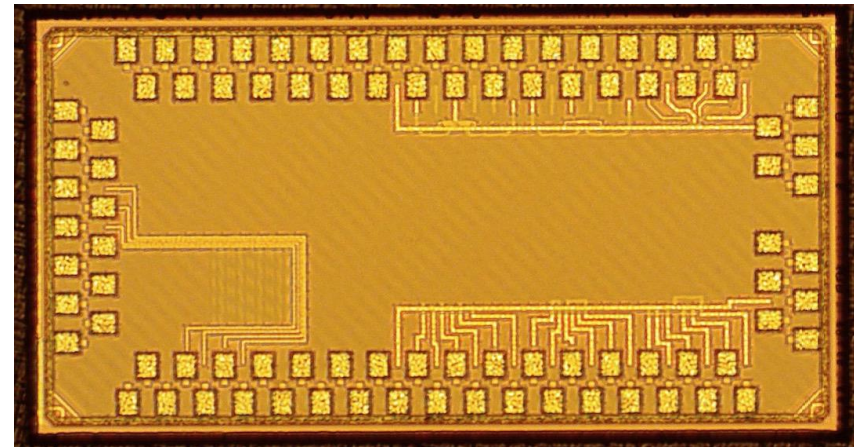
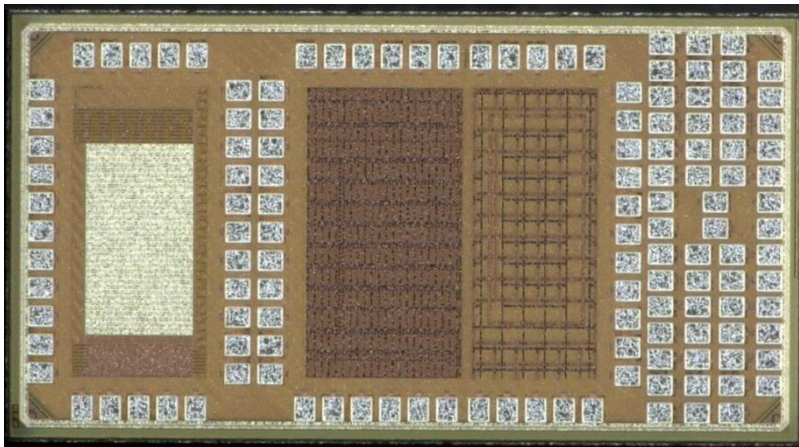
Microelectronics

A. Rivetti (INFN) Ch de La Taille (CNRS)



- **Task 11.1. Coordination and Communication [CNRS+INFN]**
- **Task 11.2. Exploratory study of advanced CMOS (28 nm)**
 - INFN PV, AGH, CNRS CPPM, UBONN
 - Explore advanced 28 nm CMOS for future trackers AGH, CNRS CPPM
 - Design and test front-end prototypes INFN PV, UBONN
 - Milestone MS45 and deliverable D11.1
- **Task 11.3. Networking and ASICs for other WPs (65/130 nm)**
 - AGH, CNRS OMEGA, IP2I, DESY, INFN (BA, BO, PV, TO) Uni Heidelberg, WEEROC (industry)
 - Cold and timing ASICs in 65/130nm CMOS : CNRS OMEGA, IP2I
 - MPGD readout ASICs : INFN (BO, TO)
 - Silicon and SiPM readout ASICs for future colliders and timing applications : AGH, CNRS OMEGA, DESY, UniH, WEEROC
 - Milestone MS46 and deliverable D11.2

- D11.1 : MPW in 28 nm
 - 2 chips submitted by CNRS/CPPM and INFN PV/BG fabricated mid 2023
 - Deliverable exists but report delayed



R&D on hybrid pixels

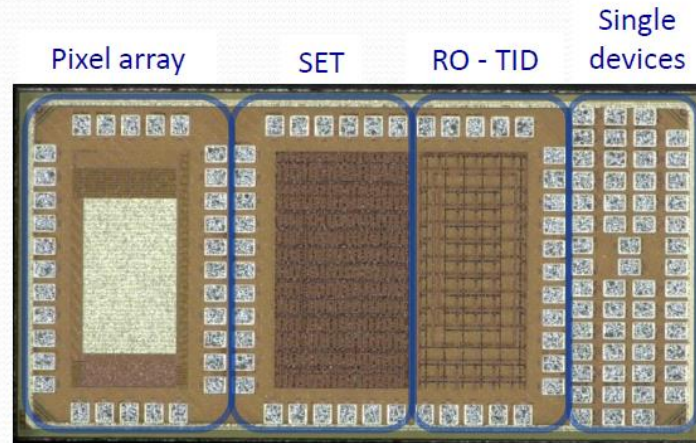
- Process qualification in terms of performance for analog, low-power and low-noise circuits
- Architecture studies
- Fast charge amplifier array

Study of Single Event Effects (SEE)

- Measure the SET cross-section
- Measure the SET pulse width with a good resolution < 20 ps
- Measure the effect of the std cell size

TID tests and qualification

- Compatibility with typical dose levels for future projects
- 28 nm process device qualification
- Gate delay evolution with TID and the effect of the std cell size
- TID Effects modeling → Analog and digital simulations with TID effects



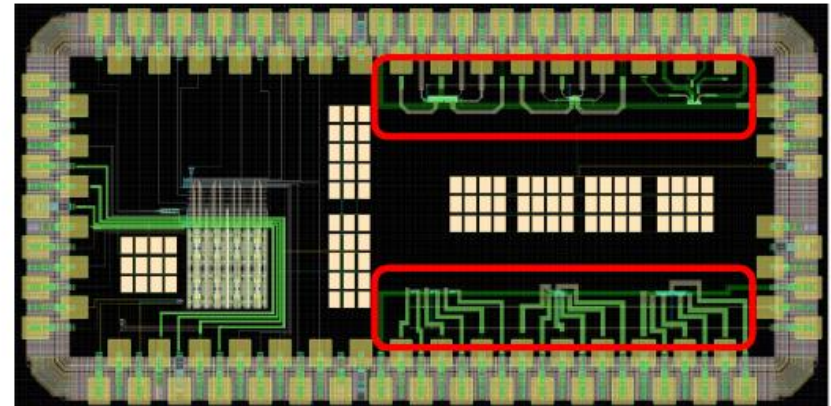
Mini@sics of 2×1 mm² received June 2024, consisting of 4 main blocks

- Analog pixel array (25×25 μm^2) with Fast charge amplifiers for high time resolution
- SET test structures
- Ring Oscillators for TID tests on digital standard cells
- Test structures for TID tolerance studies

Technology characterization

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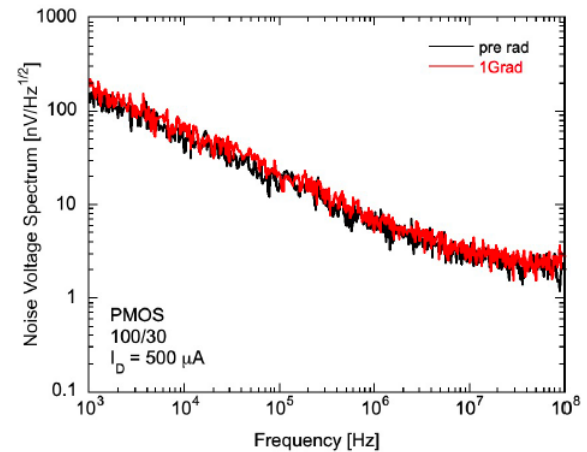
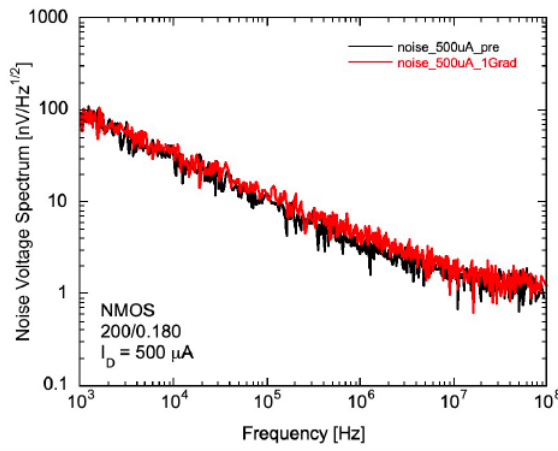
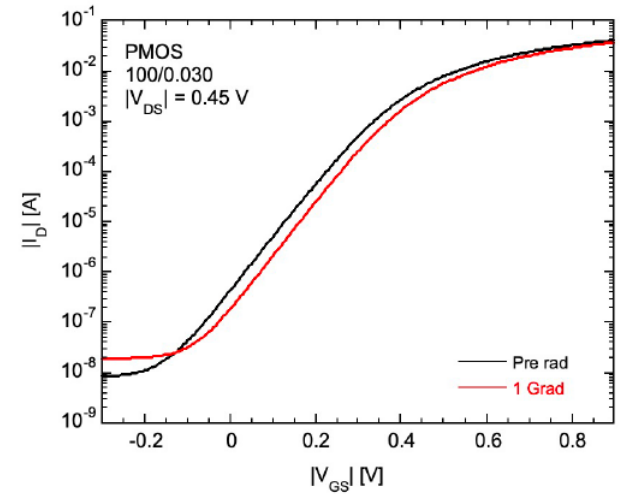
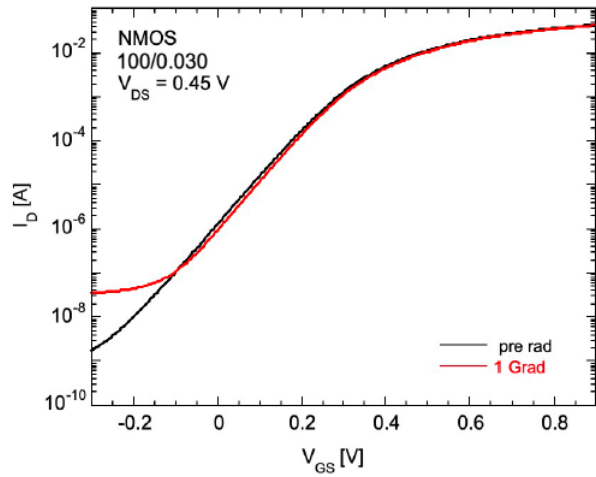
- 18 differently sized core, standard-threshold devices, both P-channel and N-channel in triple well
 - channel length: 30 nm, 60 nm and 180 nm
 - channel width: 100 μm , 200 μm and 600 μm (finger width $W_f = 2.5 \mu\text{m}$ \rightarrow 40, 80 and 240 fingers)



- **Static and signal parameters** measured with an Agilent B1500A Semiconductor Parameter Analyzer
- **Noise power spectral density** measurements carried out with an HP4395A Network/Spectrum Analyzer and a noise amplification system
 - Drain current in DUTs: from 50 μA to 500 μA \rightarrow low power operation as in high density front-end circuits

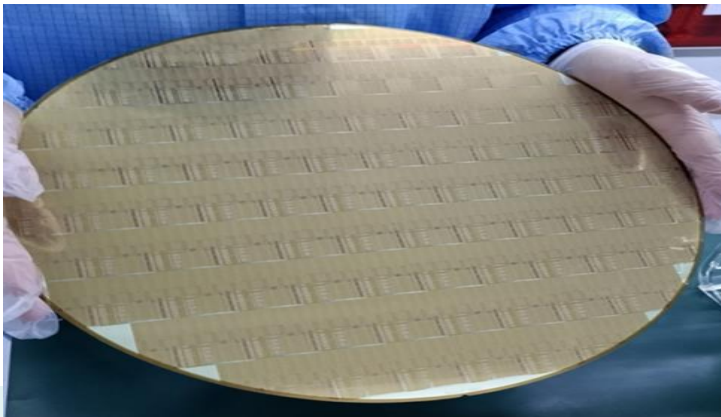
Ionizing radiation effects

- Investigated devices **irradiated up to 1 Grad(SiO₂)** total dose with X-rays (5.5 Mrad/h dose rate)
- MOSFETs biased during irradiation in the **worst-case condition**
- Slight increase in drain leakage current after irradiation
- **Limited threshold voltage changes** (depending on MOS polarity and geometry)
- Up to 1 Grad, NMOS and PMOS do not feature significant change in their **noise properties** after irradiation



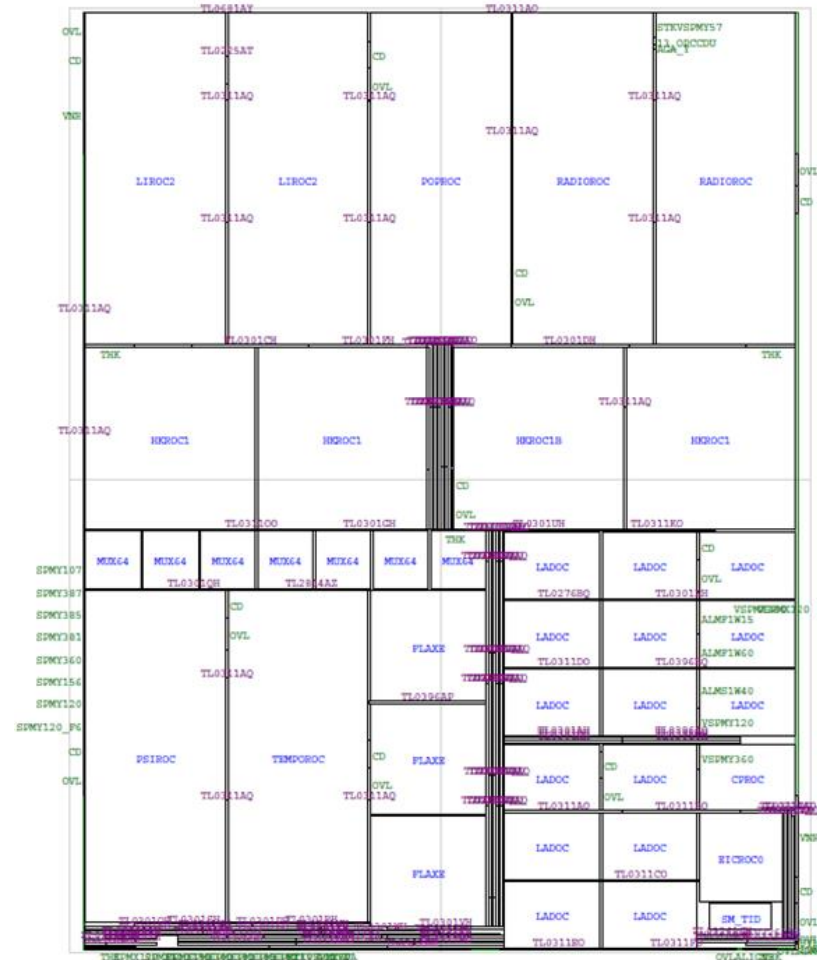
Thanks to Serena Mattiazzo and Devis Pantano (INFN PD) for their valuable support during the irradiation campaign!

- D11.2 : MPW in 130 nm
 - AIDA participation in a 130nm engineering run
 - ~25% of the reticle area (total cost 300k€)
 - Fabricated in may 23 received jan 24
- 5 chips from AIDA :
 - FLAXE (AGH) : Si/GaAs readout
 - EICROC (OMEGA/AGH/CEA) : LGAD readout
 - CPROC (OMEGA) : RISC5
 - LIROC (WEEROC) : SiPM timing
 - PSIROC (WEEROC) : Si readout

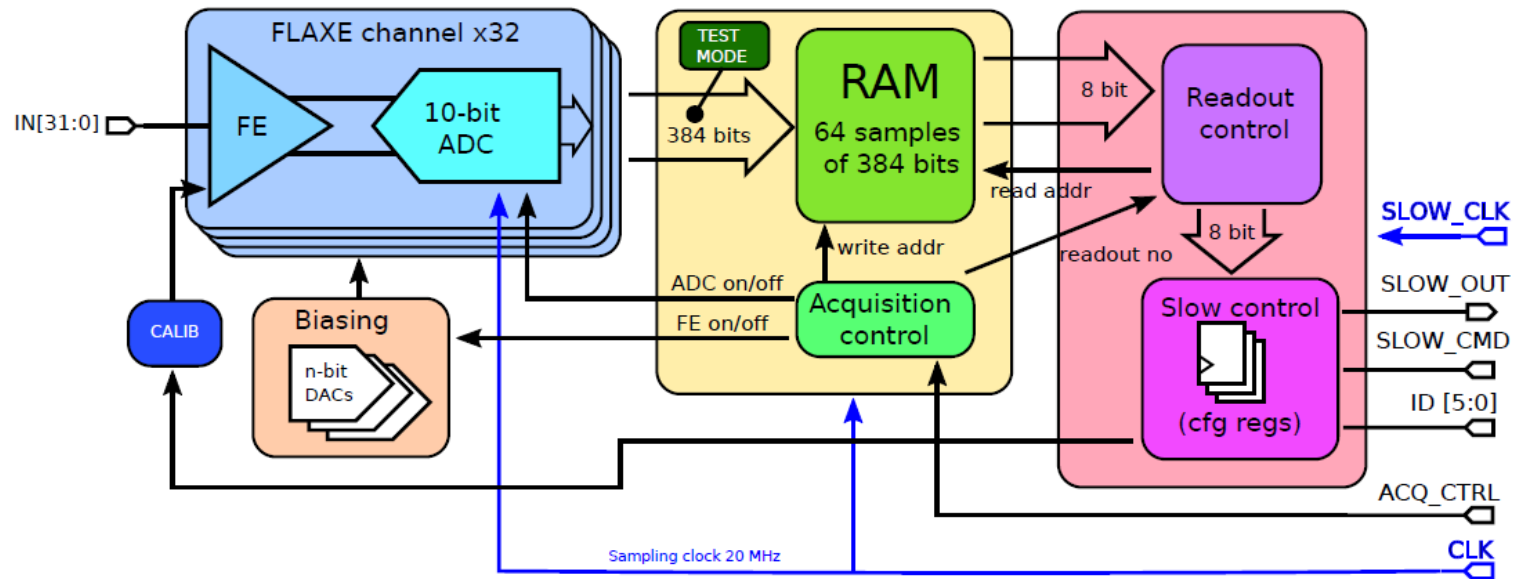


Layout Draft of E-ITO-TMSS02-001

(As of 2023-08-08 21:50:08 GMT+8)



Activities in CMOS 130nm FLAXE ASIC for ECAL-p in LUXE experiment



- FLAXE is a modified 32-channel FLAME in CMOS 130nm without high speed serialisers&transmitters – readout rate in LUXE ~10 Hz
- More than 1000 FLAXE chips were produced. Sent for dicing and packaging recently...

Applications for LIROC



- QUANTUM : True Random Number Generation : Random Power spa
- LIDAR : atmospheric LIDAR : ADS / CNES
- LIDAR : Onera
- LIDAR : ISRO
- LIDAR : Leica Geosystem

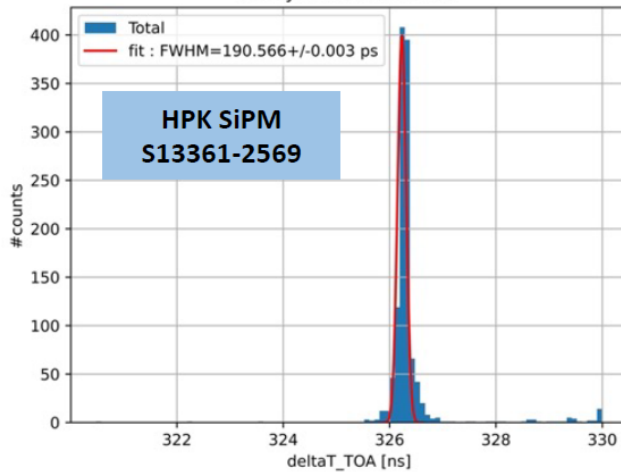


Liroc-picoTDC system: Improved time resolution (SPTR)

HPK SiPM S13361-2050NE-08

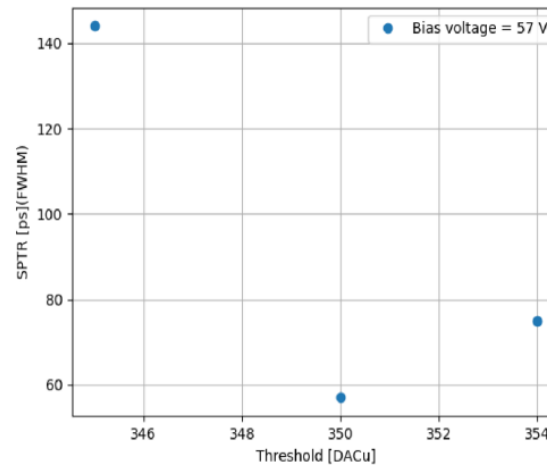
TOA Distribution

Delay: Time Difference



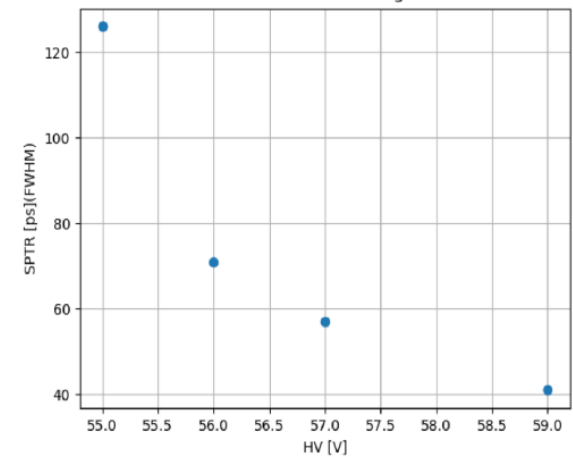
SPTR vs. Threshold

SPTR vs. ASIC Threshold



SPTR vs. Bias Voltage

SPTR vs. Bias Voltage



→ TOA measurement: best SPTR HPK S13361-2569 is 191 ps (FWHM) at 57 V .

→ Improved SPTR for a standard HPK S13361-2050NE-08: 58 ps (picoTDC) compared to 167

- 2 main pillars in AIDA INOVA
 - Explore 28 nm technology performance for HEP
 - Provide readout ASICs in 130nm for other WPs
- 2 fabrications done in 2023 to match these objectives
 - Milestones MS45/46 and deliverables 11.2/11.3
- First results shown at the annual meeting, more to come...
 - Complex chips => long testing time
- More designs also continuing in 28, 65 and 130 nm...
- At least 3 publications (AGH), probably more to be counted

- 2 Milestones and 2 deliverables
 - MS 11.1 and 11.2 (MS45 MS46) passed end 2022
 - D11.1 and 11.2 are the corresponding chips



MS11.1	Design review of 28 nm MPW	11.2	18	report
MS11.2	design review of 65/130 nm run	11.3	18	report

Deliverables related to WP11	
D11.1: MPW 28 nm <i>The deliverable is a multi-project wafer fabrication with the different test ASICs in CMOS 28 nm</i>	24
D11.2: MPW 65/130 nm <i>The deliverable is a multi-project wafer fabrication with ASICs in CMOS 65 and/or 130 nm that can be used to readout detectors from the other WPs and in particular WP8</i>	24
D11.3: Measurement reports <i>Each of the ASIC fabricated in the 2 previous deliverables will have its design and performance documented in a report</i>	42